

AAT8303 20V P-Channel Power MOSFET

General Description

The AAT8303 is a low threshold P Channel MOS-FET designed for the battery, cell phone, and PDA markets. Using AnalogicTech™'s proprietary ultrahigh density Trench technology, and space saving small outline J-lead package, performance superior to that normally found in a larger footprint has been squeezed into the area of a TSOP6 package.

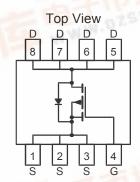
Features

- $V_{DS(MAX)} = -20V$
- I_{D(MAX)} 1 = -10A @ 25°C
- Low R_{DS(ON)}:
 - 14 m Ω @ $V_{GS} = -4.5V$
 - 24 m Ω @ V_{GS} = -2.5V

Applications

- **Battery Packs**
- Cellular & Cordless Telephones
- Battery-powered portable equipment WWW.DZSC.COM
- **Load Switches**

TSOPJW-8 Package



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Description	Value	Units		
V _{DS}	Drain-Source Voltage		-20	V	
V _{GS}	Gate-Source Voltage		±12		
I _D	Continuous Drain Current @ T _J =150°C ¹	$T_A = 25^{\circ}C$	±10		
		T _A = 70°C	±8	Α	
I _{DM}	Pulsed Drain Current ²		±48	170	
I _S	Continuous Source Current (Source-Drain Diode) 1		-2.3		
P _D	Maximum Power Dissipation ¹	$T_A = 25^{\circ}C$	2.3	w W	
		$T_A = 70^{\circ}C$	1.5	VV	
T _J , T _{STG}	Operating Junction and Storage Temperature Range		-55 to 150	°C	

Thermal Characteristics

Symbol	Description	Тур	Max	Units
$R_{\theta JA}$	Junction-to-Ambient steady state 1	86	105	°C/W
$R_{\theta JA2}$	Junction-to-Ambient t<5 seconds 1	44	54	°C/W
$R_{\theta JF}$	Junction-to-Foot 1	27	32	°C/W





Symbol	Description	Conditions	Min	Тур	Max	Units	
DC Chara	DC Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20			V	
	Drain-Source ON-Resistance ²	V_{GS} =-4.5V, I_D =-10A		11	14	mΩ	
R _{DS(ON)}		V_{GS} =-2.5V, I_{D} =-7.6A	18 24		11122		
I _{D(ON)}	On-State Drain Current ²	V_{GS} =-4.5V, V_{DS} =-5V (Pulsed)	-48			Α	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=-250\mu A$	-0.6			V	
I _{GSS}	Gate-Body Leakage Current	V_{GS} =±12V, V_{DS} =0V			±100	nA	
1	Drain Source Leakage Current	V_{GS} =0V, V_{DS} =-20V			-1	Δ	
I _{DSS}	Drain Source Leakage Current	V_{GS} =0V, V_{DS} =-16V, T_J =70°C 3			-5	– μA	
g_{fs}	Forward Transconductance ²	V_{DS} =-5V, I_{D} =-10A		31		S	
Dynamic	Characteristics ³						
Q_G	Total Gate Charge	V_{DS} =-10V, R_{D} =1.0 Ω , V_{GS} =-4.5V		36			
Q_{GS}	Gate-Source Charge	V_{DS} =-10V, R_{D} =1.0 Ω , V_{GS} =-4.5V		5		nC	
Q_{GD}	Gate-Drain Charge	V_{DS} =-10V, R_{D} =1.0 Ω , V_{GS} =-4.5V		13			
t _{D(ON)}	Turn-ON Delay	V_{DS} =-10V, V_{GS} =-4.5V, R_{D} =1.0 Ω , R_{G} =6 Ω		10			
t _R	Turn-ON Rise Time	V_{DS} =-10V, V_{GS} =-4.5V, R_{D} =1.0 Ω , R_{G} =6 Ω		72			
t _{D(OFF)}	Turn-OFF Delay	V_{DS} =-10V, V_{GS} =-4.5V, R_{D} =1.0 Ω , R_{G} =6 Ω		78		ns ns	
t _F	Turn-OFF Fall Time	V_{DS} =-10V, V_{GS} =-4.5V, R_{D} =1.0 Ω , R_{G} =6 Ω		108			
Source-Drain Diode Characteristics							
V _{SD}	Source-Drain Forward Voltage ²	V _{GS} =0, I _S =-10A			-1.1	V	
I _S	Continuous Diode Current ¹				-2.3	Α	

Note 1: Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5 second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications. $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$ where the foot thermal reference is defined as the normal solder mounting surface of the device's leads. $R_{\theta JF}$ is guaranteed by design, however $R_{\theta CA}$ is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

Note 2: Pulse test: Pulse Width = 300 μs

Note 3: Guaranteed by design. Not subject to production testing.

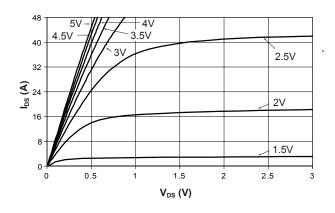
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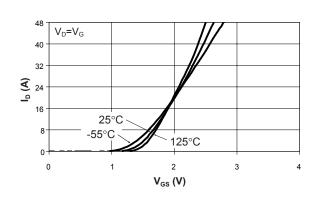
Typical Characteristics

(T₁ = 25°C unless otherwise noted)

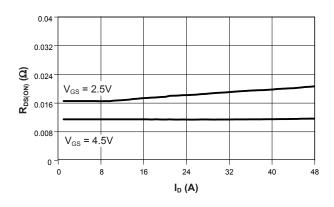
Output Characteristics



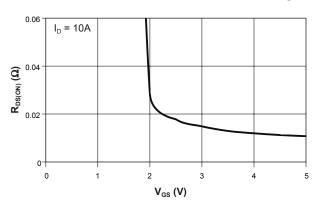
Transfer Characteristics



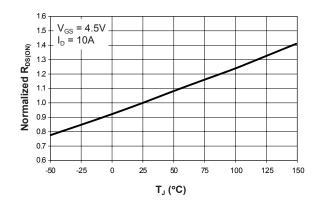
On-Resistance vs. Drain Current



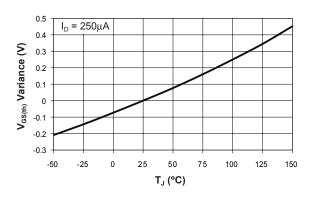
On-Resistance vs. Gate to Source Voltage



On-Resistance vs. Junction Temperature



Threshold Voltage



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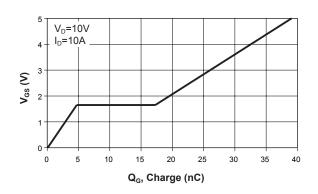
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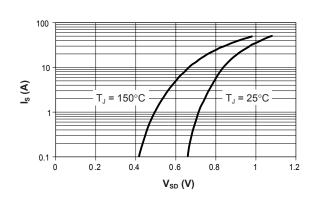
Typical Characteristics

 $(T_1 = 25^{\circ}C \text{ unless otherwise noted})$

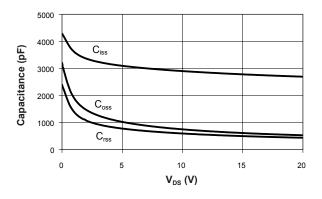
Gate Charge



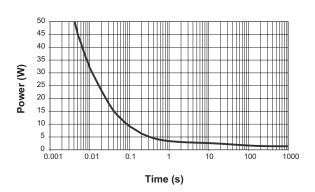
Source-Drain Diode Forward Voltage



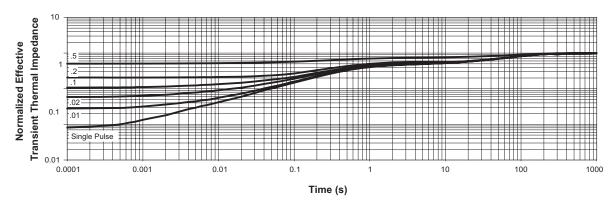
Capacitance



Single Pulse Power, Junction to Ambient



Transient Thermal Response, Junction to Ambient



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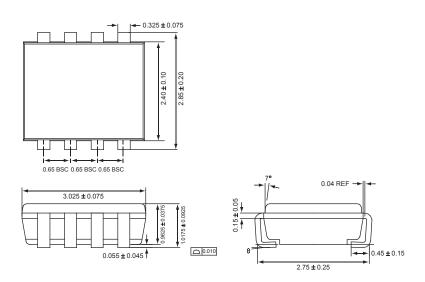
Ordering Information

Package	Marking ¹	Part Number (Tape and Reel)
TSOPJW-8	JXXYY	AAT8303ITS-T1

Note 1: XYY = assembly and date code.

Package Information

TSOPJW-8



All dimensions in millimeters.

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